LM185-1.2-N/LM285-1.2-N/LM385-1.2-N Micropower Voltage Reference Diode

Check for Samples: LM185-1.2-N, LM285-1.2-N, LM385-1.2-N

FEATURES

- **±1% and 2% Initial Tolerance**
- **Operating Current of 10μA to 20mA**
- **1Ω Dynamic Impedance**
- **Low Temperature Coefficient**
- **Low Voltage Reference—1.235V**
- **2.5V Device and Adjustable Device Also Available**
- **LM185-2.5 Series and LM185 Series, respectively**

DESCRIPTION

The LM185-1.2-N/LM285-1.2-N/LM385-1.2-N are micropower 2-terminal band-gap voltage regulator diodes. Operating over a 10μA to 20mA current range, they feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming is used to provide tight voltage tolerance. Since the LM185-1.2-N band-gap reference uses only transistors and resistors, low noise and good long term stability result.

Careful design of the LM185-1.2-N has made the device exceptionally tolerant of capacitive loading, making it easy to use in almost any reference application. The wide dynamic operating range allows its use with widely varying supplies with excellent regulation.

The extremely low power drain of the LM185-1.2-N makes it useful for micropower circuitry. This voltage reference can be used to make portable meters, regulators or general purpose analog circuitry with battery life approaching shelf life.

Further, the wide operating current allows it to replace older references with a tighter tolerance part.

The LM185-1.2-N is rated for operation over a −55°C to 125°C temperature range while the LM285-1.2-N is rated −40°C to 85°C and the LM385-1.2-N 0°C to 70°C. The LM185-1.2-N/LM285-1.2-N are available in a hermetic TO package and the LM285-1.2-N/LM385-1.2-N are also available in a low-cost TO-92 molded package, as well as SOIC and SOT-23.

CONNECTION DIAGRAM

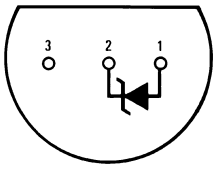
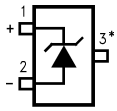


Figure 1. T0-92 Package (LP)
(Bottom View)



* Pin 3 is attached to the Die Attach Pad (DAP) and should be connected to Pin 2 or left floating.

Figure 2. SOT-23

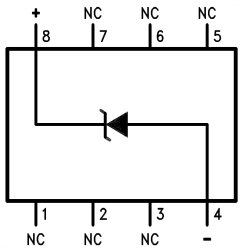


Figure 3. SOIC Package

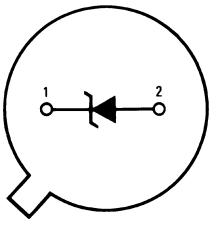


Figure 4. TO Package (NDV)
(Bottom View)

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS(1)(2)(3)

Reverse Current	30mA
Forward Current	10mA
Operating Temperature Range (4)	
LM185-1.2-N	−55°C to +125°C
LM285-1.2-N	−40°C to +85°C
LM385-1.2-N	0°C to 70°C
ESD Susceptibility (5)	2kV
Storage Temperature	−55°C to +150°C
Soldering Information	
TO-92 package: 10 sec.	260°C
TO package:10 sec.	300°C
SOIC and SOT-23 Pkg.	
Vapor phase (60 sec.)	215°C
Infrared (15 sec.)	220°C
See AN-450 “Surface Mounting Methods and Their Effect on Product Reliability” for other methods of soldering surface mount devices.	

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional. For specifications and test conditions, see the Electrical Characteristics. The specifications apply only for the test conditions listed.
(2) Refer to RETS185H-1.2 for military specifications.
(3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
(4) For elevated temperature operation, see Table 1.
(5) The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin.

Table 1. $T_{J(max)}$ for Elevated Temperature Operation

DEVICE	$T_{J(max)}$ (°C)
LM185-1.2-N	150
LM285-1.2-N	125
LM385-1.2-N	100

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ELECTRICAL CHARACTERISTICS(1)

Parameter	Conditions	Typ	LM185-1.2-N LM185BX-1.2-N LM185BY-1.2-N LM285-1.2-N LM285BX-1.2-N LM285BY-1.2-N		LM385B-1.2-N LM385BX-1.2-N LM385BY-1.2-N		LM385-1.2-N		Units (Limit)
			Tested Limit (2) (3)	Design Limit (4)	Tested Limit (2)	Design Limit (4)	Tested Limit (2)	Design Limit (4)	
Reverse Breakdown Voltage	T_A = 25°C, 10µA ≤ I_R ≤ 20mA	1.235	1.223 1.247		1.223 1.247		1.205 1.260		V(Min) V(Max)
Minimum Operating Current		8	10	**20**	15	**20**	15	**20**	µA
	LM385M3-1.2-N						10	**15**	(Max)
Reverse Breakdown Voltage Change with Current	10µA ≤ I_R ≤ 1mA		1	**1.5**	1	**1.5**	1	**1.5**	mV (Max)
	1mA ≤ I_R ≤ 20mA		10	**20**	20	**25**	20	**25**	mV (Max)
Reverse Dynamic Impedance	I_R = 100µA, f = 20Hz	1							Ω
Wideband Noise (rms)	I_R = 100µA, 10Hz ≤ f ≤ 10kHz	60							µV
Long Term Stability	I_R = 100µA, T = 1000 Hr, T_A = 25°C ±0.1°C	20							ppm
Average Temperature Coefficient (5)	I_R = 100µA X Suffix Y Suffix All Others		 **30** **50**	 **150**	 **30** **50**	 **150**	 	 **150**	 ppm/°C ppm/°C ppm/°C (Max)

(1) Parameters identified with boldface type apply at temperature extremes. All other numbers apply at T_A = T_J = 25°C.
(2) Production tested.
(3) A military RETS electrical specification is available on request.
(4) Specified by design. Not production tested. These limits are not used to calculate average outgoing quality levels.
(5) The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures between the operating T_{MAX} and T_{MIN}, divided by T_{MAX} − T_{MIN}. The measured temperatures are −55°C, −40°C, 0°C, 25°C, 70°C, 85°C, 125°C.

THERMAL CHARACTERISTICS

Thermal Resistance	TO-92	TO	SOIC	SOT-23
θ_{JA} (junction to ambient)	180°C/W (0.4″ leads) 170°C/W (0.125″ leads)	440°C/W	165°C/W	283°C/W
θ_{JC} (junction to case)	N/A	80°C/W	N/A	N/A

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TYPICAL PERFORMANCE CHARACTERISTICS

Reverse Characteristics

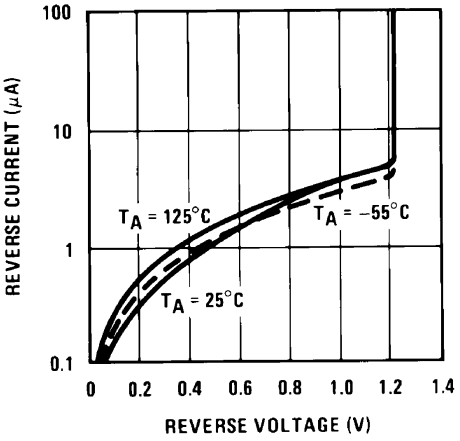

Figure 5.

Reverse Characteristics

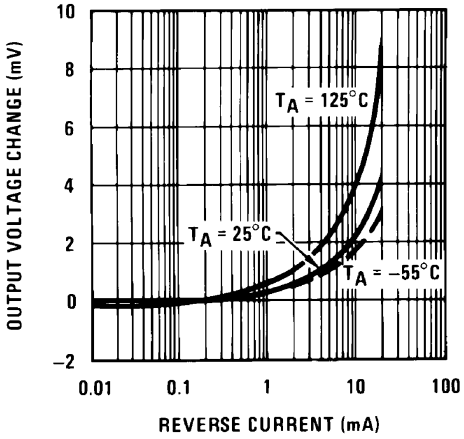

Figure 6.

Forward Characteristics

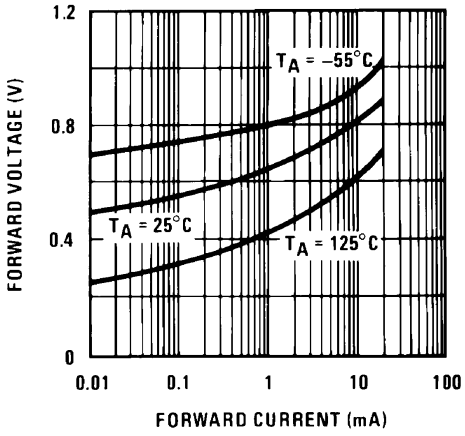

Figure 7.

Temperature Drift of 3 Representative Units

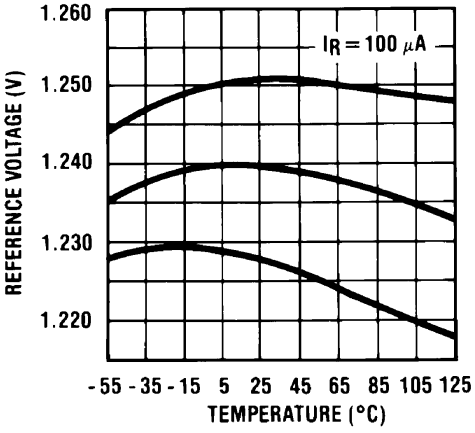

Figure 8.

Reverse Dynamic Impedance

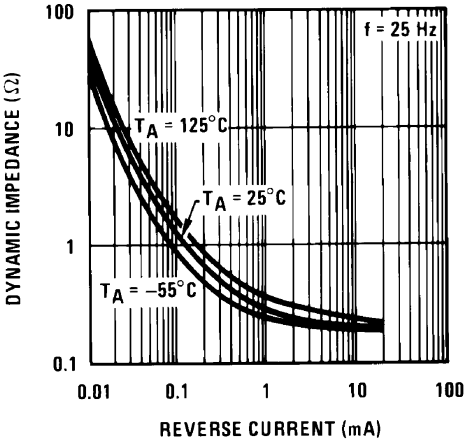

Figure 9.

Reverse Dynamic Impedance

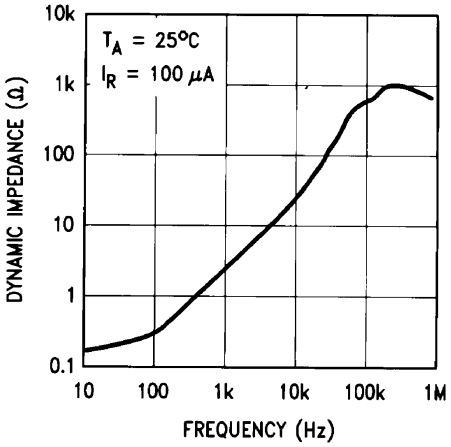

Figure 10.

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Noise Voltage

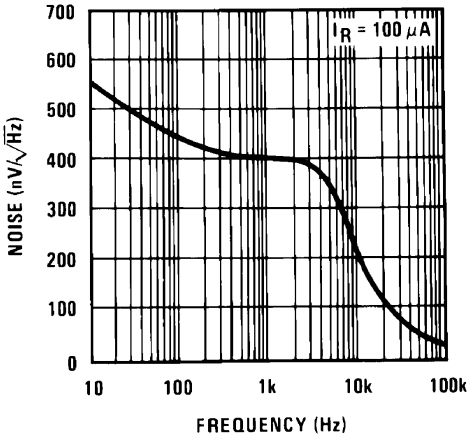


Figure 11.

Filtered Output Noise

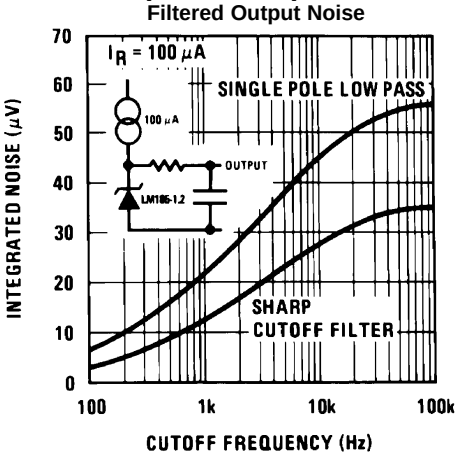


Figure 12.

Response Time

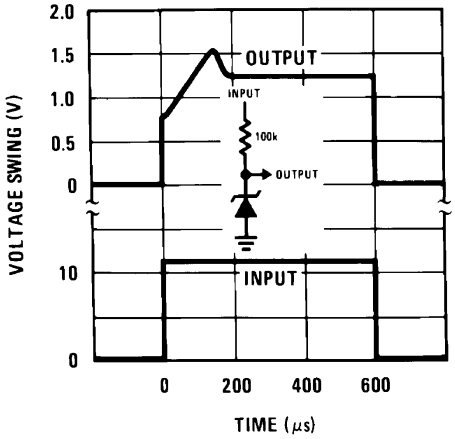


Figure 13.

TYPICAL APPLICATIONS

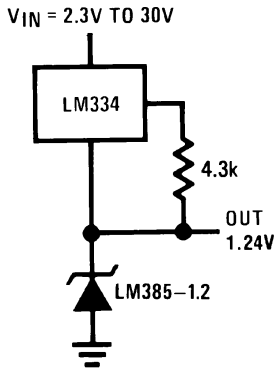


Figure 14. Wide Input Range Reference

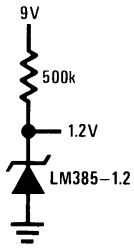


Figure 15. Micropower Reference from 9V Battery

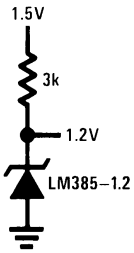
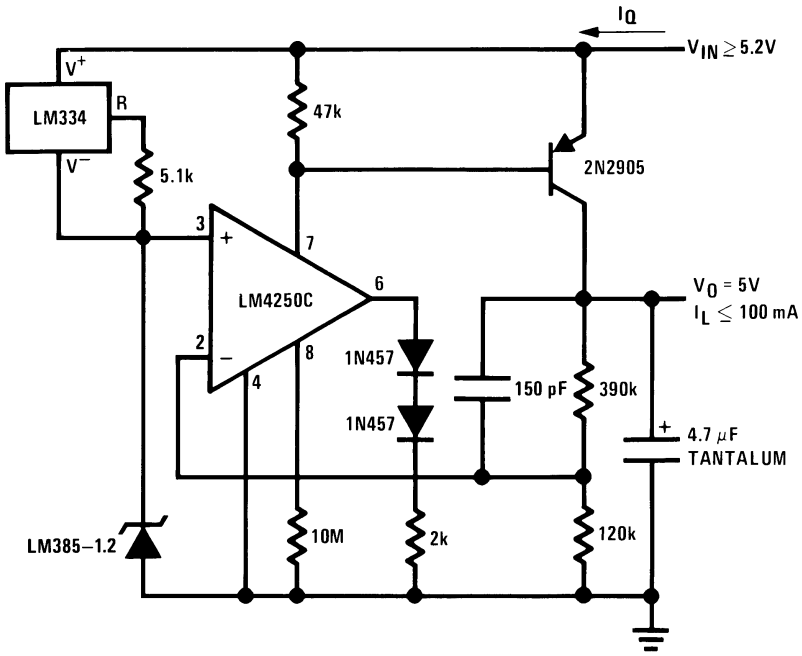


Figure 16. Reference from 1.5V Battery



*$I_Q \simeq 30\mu A$

Figure 17. Micropower* 5V Regulator

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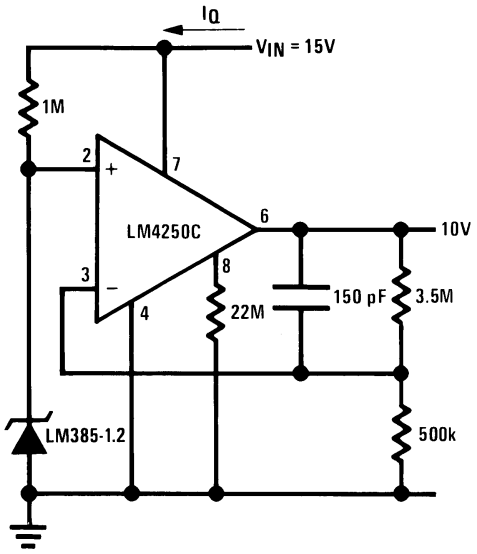


*I_Q ≈20µA standby current

Figure 18. Micropower* 10V Reference

*$I_{OUT} = \frac{1.23V}{R2}$

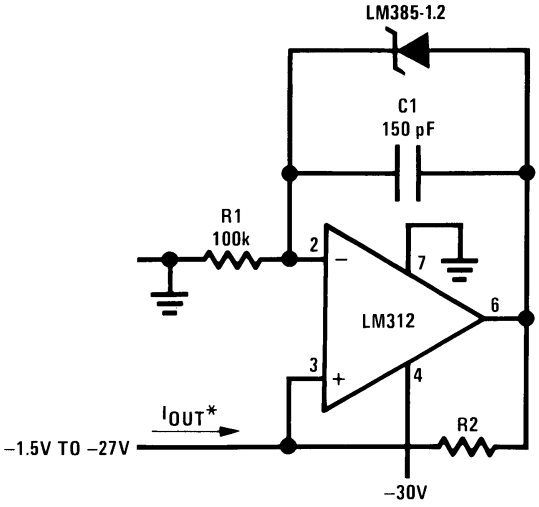


Figure 19.

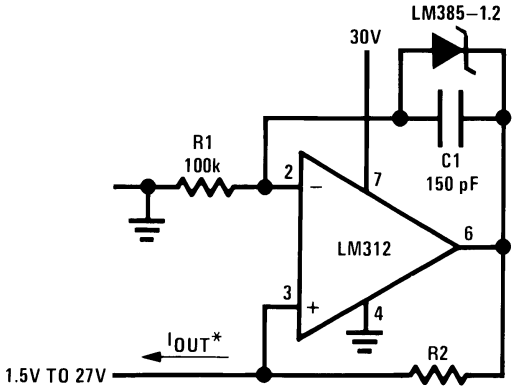
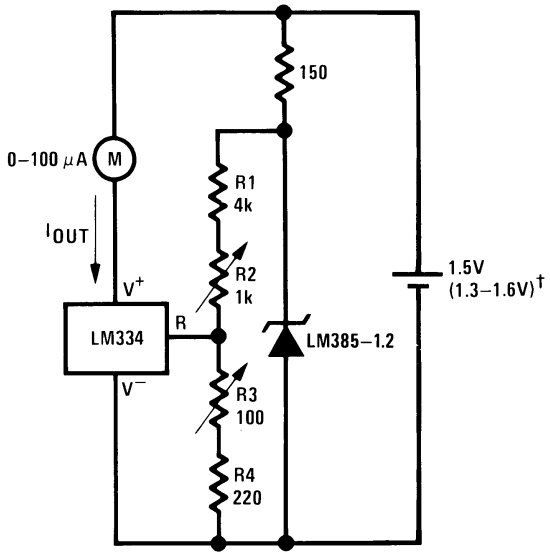


Figure 20. Precision 1µA to 1mA Current Sources

METER THERMOMETERS



Calibration

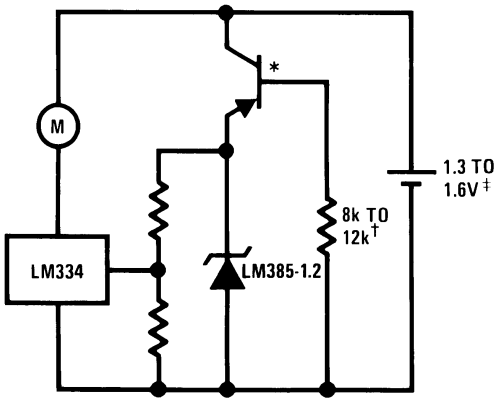
1. Short LM385-1.2-N, adjust R3 for I_{OUT}= temp at 1μA/°K
2. Remove short, adjust R2 for correct reading in centigrade

†I_Q at 1.3V≅500μA

I_Q at 1.6V≅2.4mA

Figure 21. 0°C−100°C Thermometer

Figure 22.



*2N3638 or 2N2907 select for inverse H_{FE} ≅ 5

†Select for operation at 1.3V

‡I_Q ≅ 600μA to 900μA

Figure 23. Lower Power Thermometer

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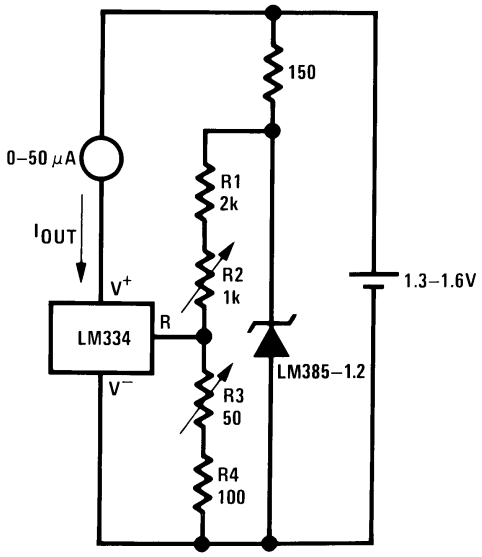
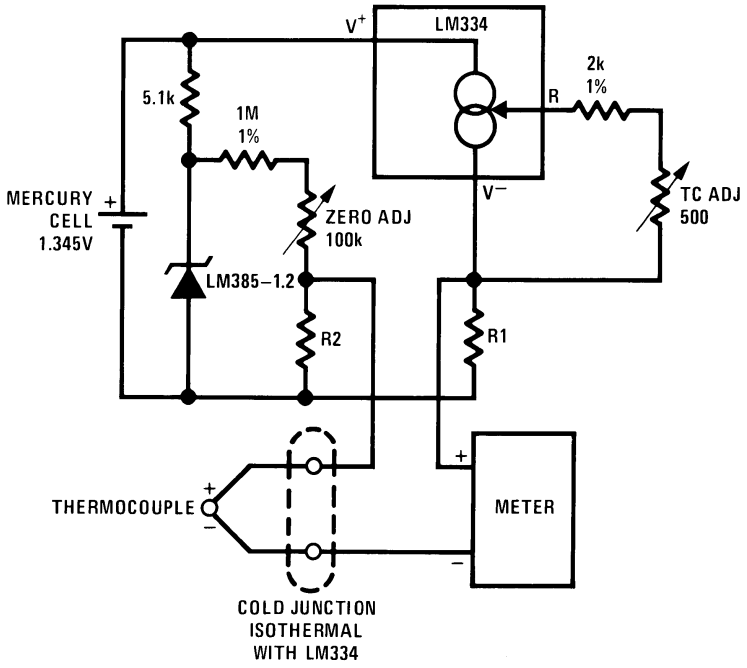


Calibration

1. Short LM385-1.2-N, adjust R3 for I_{OUT}= temp at 1.8μA/°K
2. Remove short, adjust R2 for correct reading in °F

Figure 24. 0°F−50°F Thermometer



Adjustment Procedure

1. Adjust TC ADJ pot until voltage across R1 equals Kelvin temperature multiplied by the thermocouple Seebeck coefficient.
2. Adjust zero ADJ pot until voltage across R2 equals the thermocouple Seebeck coefficient multiplied by 273.2.

Figure 25. Micropower Thermocouple Cold Junction Compensator

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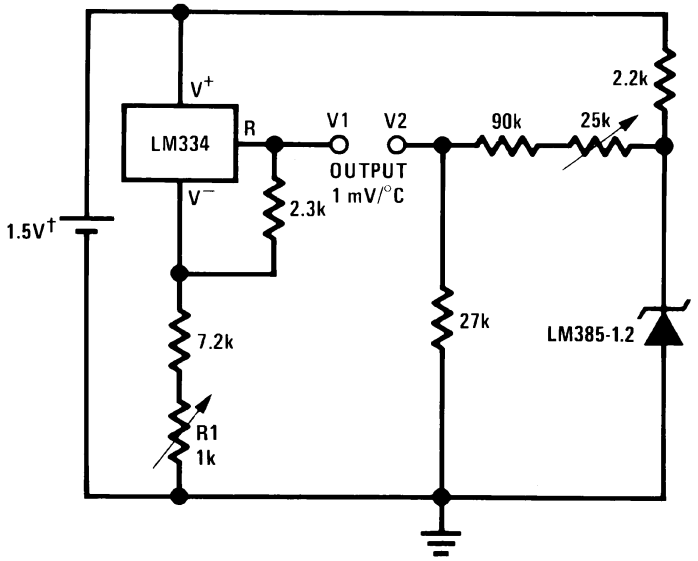
Thermocouple Type	Seebeck Coefficient (μV/°C)	R1 (Ω)	R2 (Ω)	Voltage Across R1 @ 25°C (mV)	Voltage Across R2 (mV)
J	52.3	523	1.24k	15.60	14.32
T	42.8	432	1k	12.77	11.78
K	40.8	412	953Ω	12.17	11.17
S	6.4	63.4	150Ω	1.908	1.766

Typical supply current 50μA



Calibration
1. Adjust R1 so that V1 = temp at 1mV/°K
2. Adjust V2 to 273.2mV
†I_Q for 1.3V to 1.6V battery voltage = 50μA to 150μA

Figure 26. Centigrade Thermometer

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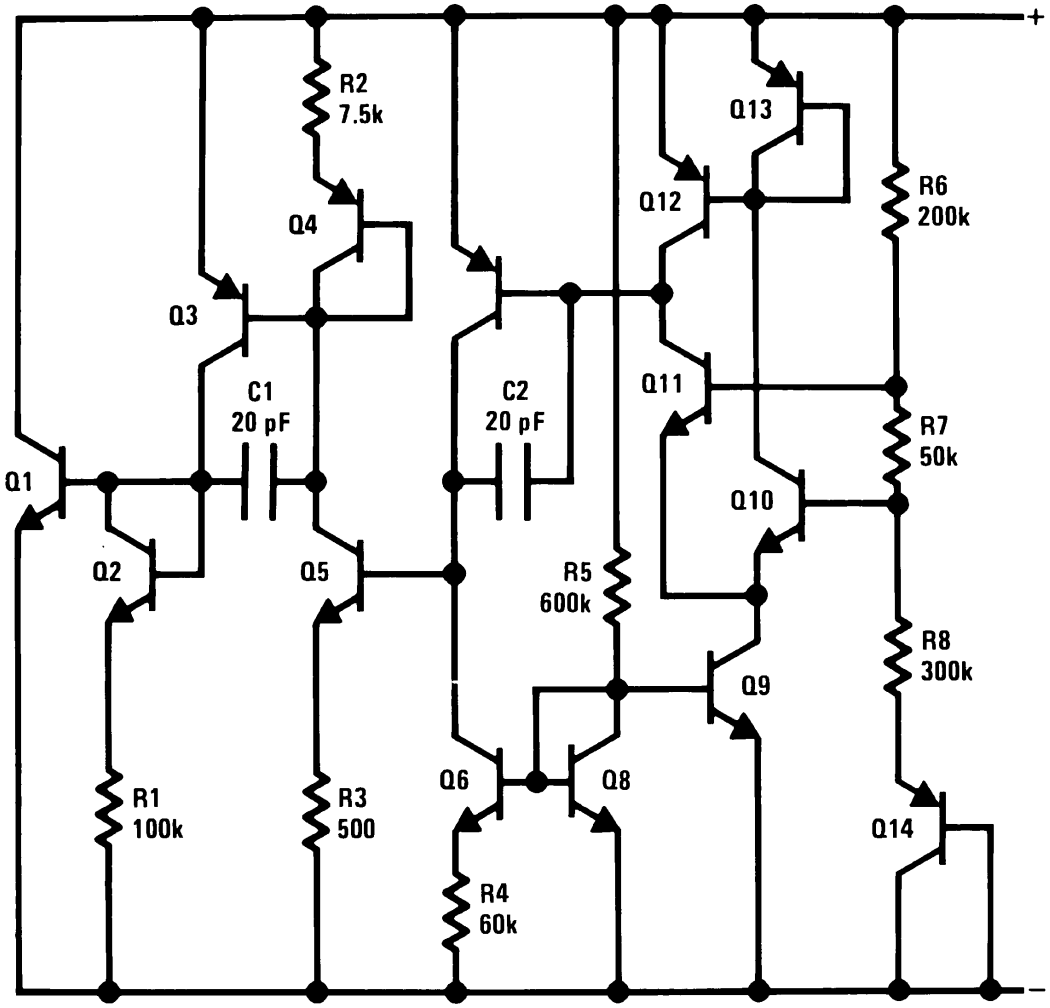
SCHEMATIC DIAGRAM



REVISION HISTORY

Changes from Revision D (April 2013) to Revision E	Page
• Changed layout of National Data Sheet to TI format	11

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM185BYH-1.2	ACTIVE	TO	NDU	2	1000	TBD	Call TI	Call TI	-55 to 125	LM185BYH1.2	Samples
LM185BYH-1.2/NOPB	ACTIVE	TO	NDU	2	1000	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM185BYH1.2	Samples
LM185H-1.2	ACTIVE	TO	NDU	2	1000	TBD	Call TI	Call TI	-55 to 125	LM185H1.2	Samples
LM185H-1.2/NOPB	ACTIVE	TO	NDU	2	1000	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM185H1.2	Samples
LM285BXM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BX M1.2	Samples
LM285BXMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BX M1.2	Samples
LM285BXZ-1.2/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		285BX Z-1.2	Samples
LM285BXZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	-40 to 85	285BX Z-1.2	Samples
LM285BYM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BY M1.2	Samples
LM285BYMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BY M1.2	Samples
LM285H-1.2	ACTIVE	TO	NDU	2	1000	TBD	Call TI	Call TI	-40 to 85	LM285H1.2	Samples
LM285H-1.2/NOPB	ACTIVE	TO	NDU	2	1000	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-40 to 85	LM285H1.2	Samples
LM285M-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM285 M1.2	Samples
LM285MX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM285 M1.2	Samples
LM285Z-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	-40 to 85	LM28 5Z-1.2	Samples
LM385BM-1.2	ACTIVE	SOIC	D	8	95	TBD	Call TI	Call TI	0 to 70	LM385 BM1.2	Samples
LM385BM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 BM1.2	Samples
LM385BMX-1.2	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 70	LM385	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
										BM1.2	
LM385BMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 BM1.2	Samples
LM385BXM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BX M1.2	Samples
LM385BXMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BX M1.2	Samples
LM385BXZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	385BX Z-1.2	Samples
LM385BYM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BY M1.2	Samples
LM385BYMX-1.2	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 70	385BY M1.2	Samples
LM385BYMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BY M1.2	Samples
LM385BYZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	385BY Z-1.2	Samples
LM385BZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	LM385 BZ1.2	Samples
LM385M-1.2	ACTIVE	SOIC	D	8	95	TBD	Call TI	Call TI	0 to 70	LM385 M1.2	Samples
LM385M-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 M1.2	Samples
LM385M3-1.2	ACTIVE	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	0 to 70	R11	Samples
LM385M3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	R11	Samples
LM385M3X-1.2	ACTIVE	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	0 to 70	R11	Samples
LM385M3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	R11	Samples
LM385MX-1.2	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 70	LM385 M1.2	Samples
LM385MX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 M1.2	Samples
LM385Z-1.2/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM385 Z-1.2	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM385Z-1.2/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM385 Z-1.2	Samples
LM385Z-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	LM385 Z-1.2	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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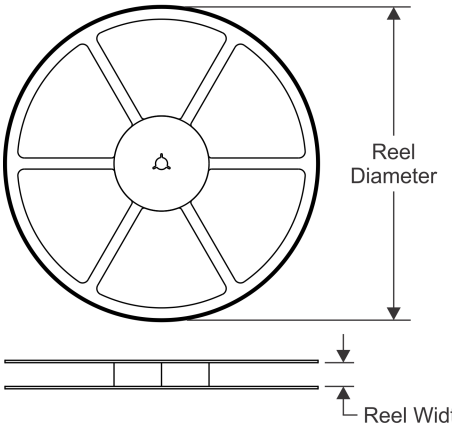
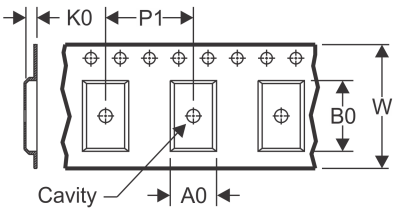
TAPE AND REEL INFORMATION

REEL DIMENSIONS

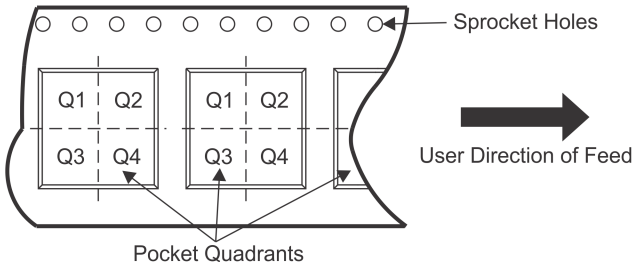


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

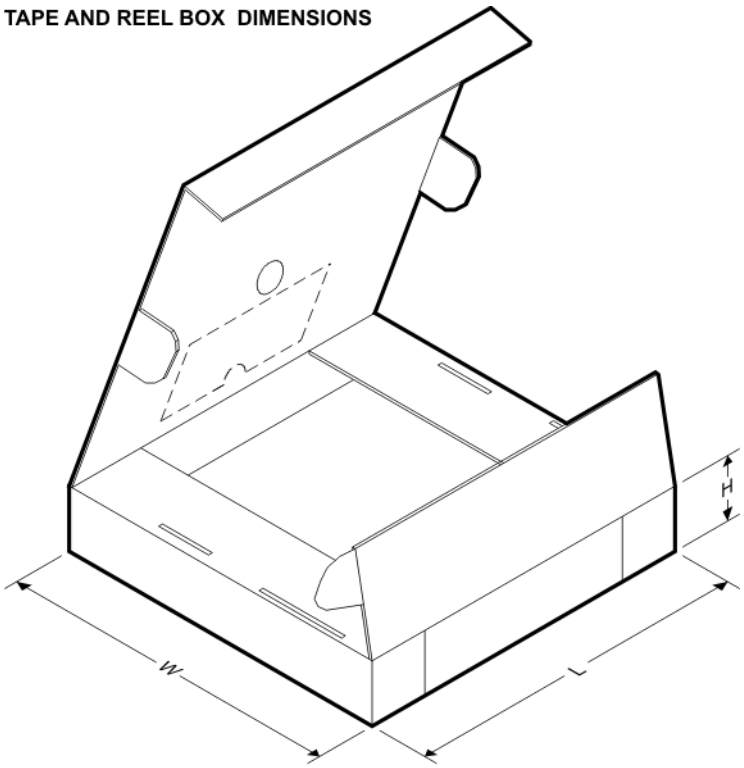
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM285BXMX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285BYMX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285MX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BMX-1.2	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BMX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BXMX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BYMX-1.2	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BYMX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385M3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3X-1.2	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385MX-1.2	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385MX-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

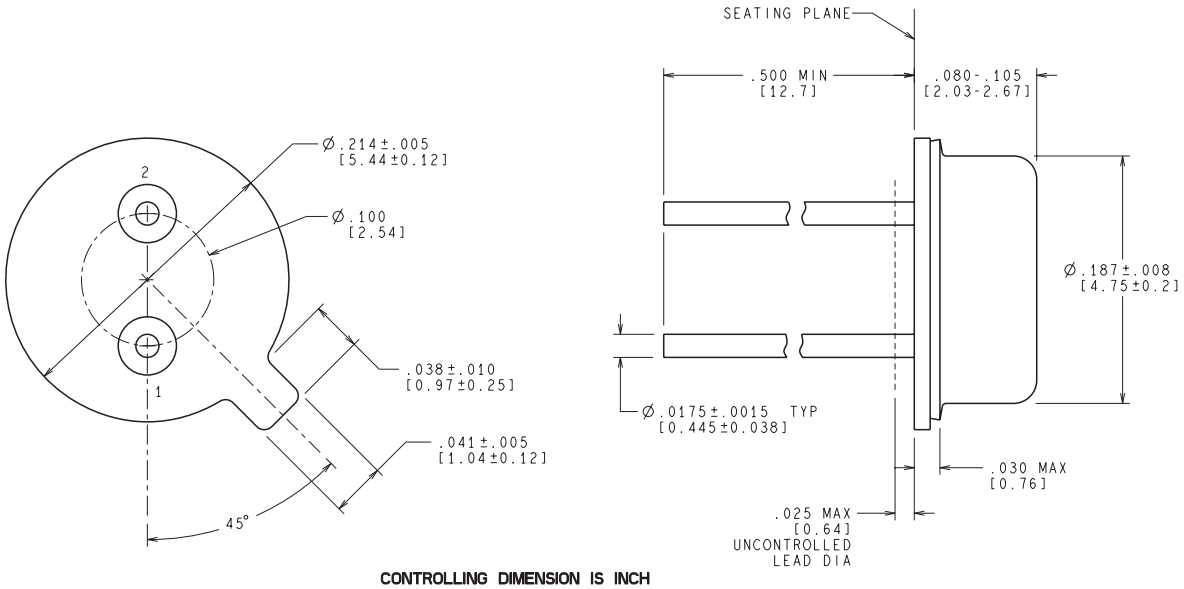
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM285BXMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285BYMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285MX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BMX-1.2	SOIC	D	8	2500	367.0	367.0	35.0
LM385BMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BXMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BYMX-1.2	SOIC	D	8	2500	367.0	367.0	35.0
LM385BYMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385M3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM385M3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM385M3X-1.2	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM385M3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM385MX-1.2	SOIC	D	8	2500	367.0	367.0	35.0
LM385MX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

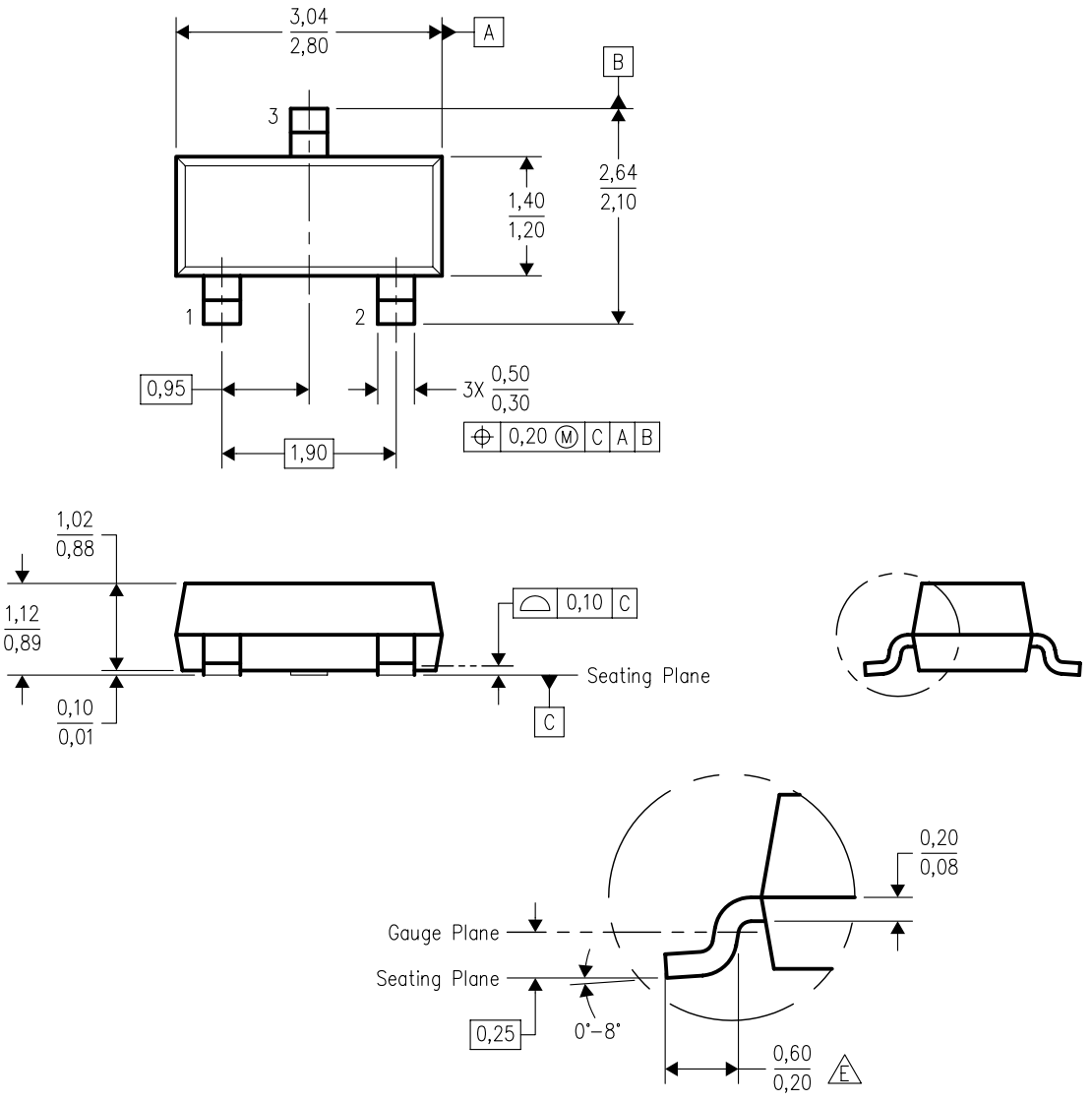
NDU0002A



CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

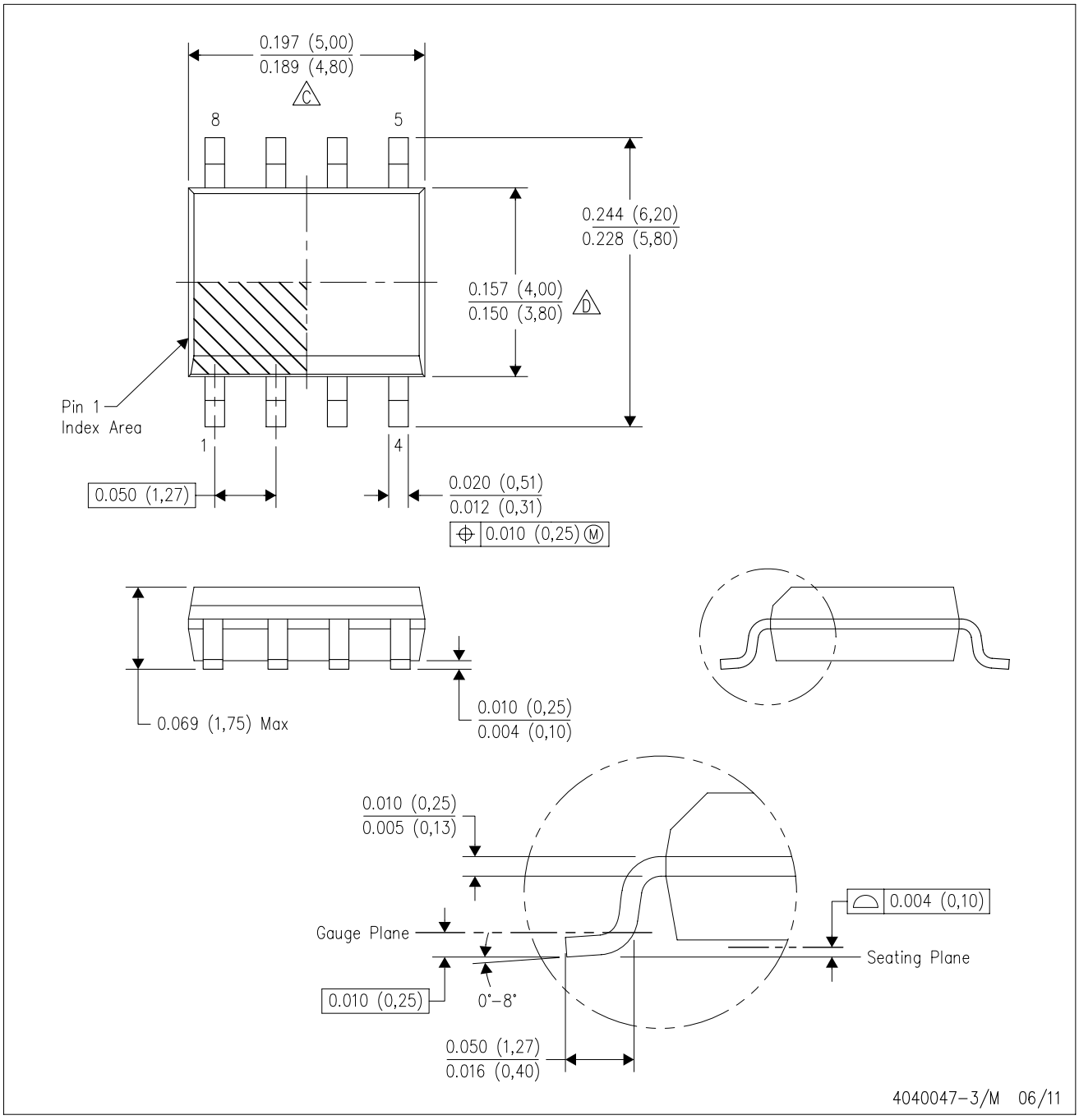
H02A (Rev F)

DBZ (R–PDSO–G3) PLASTIC SMALL–OUTLINE



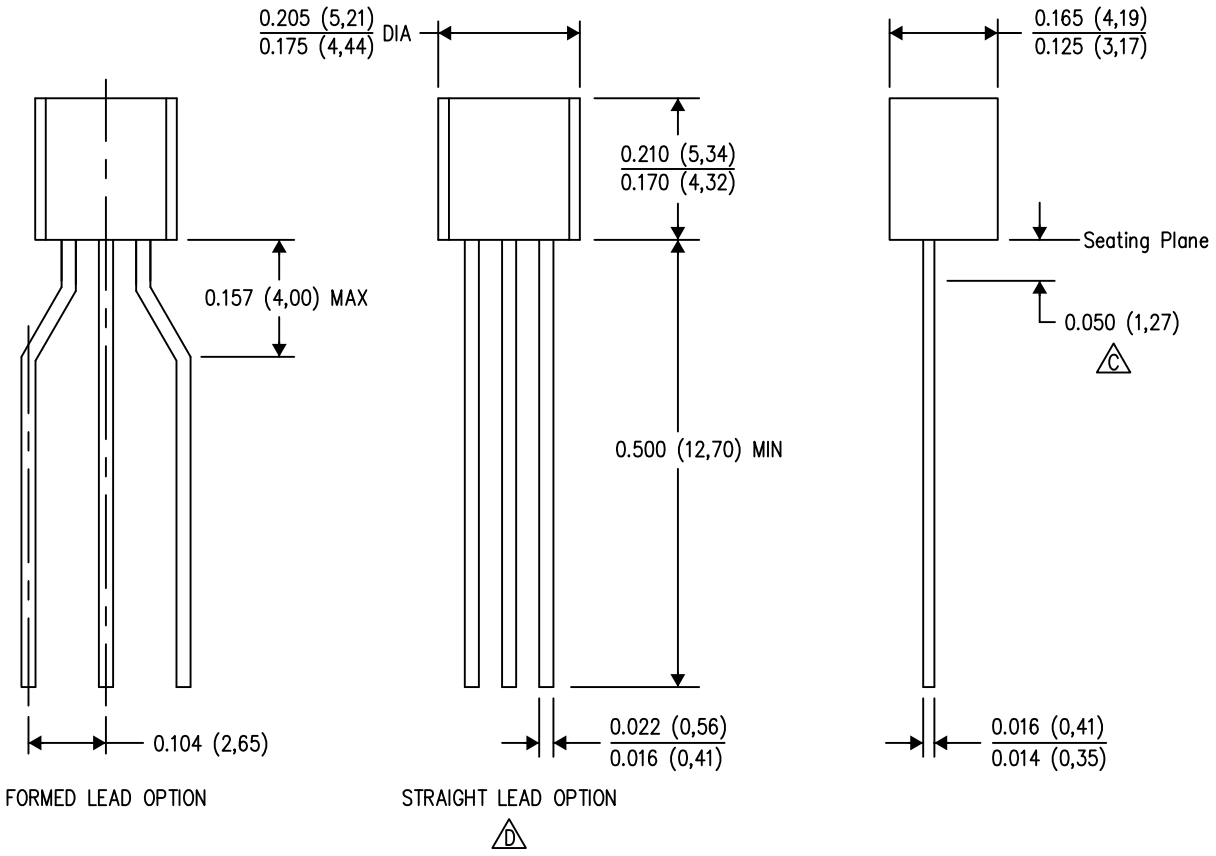
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Lead dimensions are inclusive of plating.
D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
E. Falls within JEDEC TO–236 variation AB, except minimum foot length.

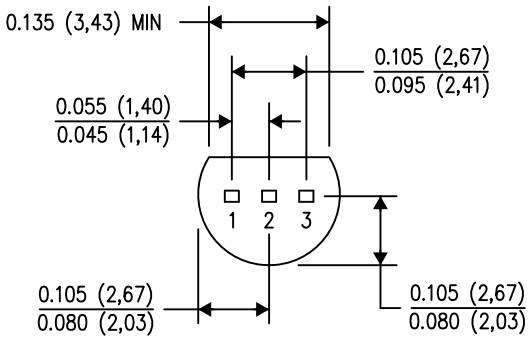
D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

LP (O–PBCY–W3) PLASTIC CYLINDRICAL PACKAGE

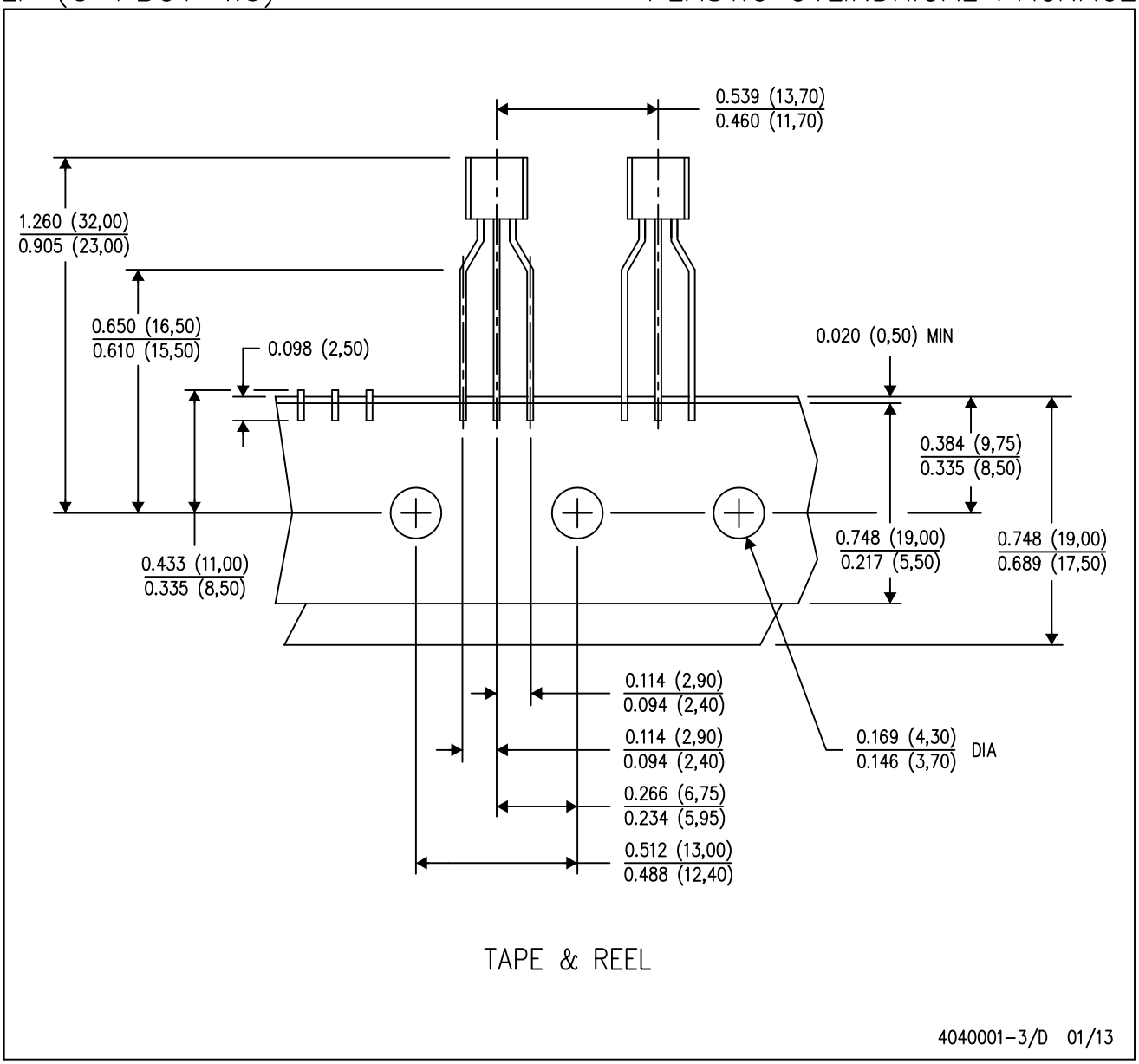




4040001–2/D 01/13

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Lead dimensions are not controlled within this area.
D. Falls within JEDEC TO–226 Variation AA (TO–226 replaces TO–92).
E. Shipping Method:
Straight lead option available in either bulk pack or tape & reel.
Formed lead option available in tape & reel or ammo pack.
Specific products can be offered in limited combinations of shipping mediums and lead options.
Consult product folder for more information on available options.

LP (O–PBCY–W3) PLASTIC CYLINDRICAL PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Tape and Reel information for the Formed Lead Option package.

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